

**DIRECT INTERCONNECT MULTI-CHIP MODULE, METHOD FOR MAKING
THE SAME AND ELECTRONIC PACKAGE COMPRISING SAME**

ABSTRACT OF THE DISCLOSURE

A multi-chip module as disclosed herein includes a first semiconductor device, a second
5 semiconductor device and a plurality of device interconnect members. The first semiconductor
device is capable of enabling functionality associated with a first circuit segment of an integrated
circuit design and includes an array of first device interconnect pads. The second semiconductor
device is capable of enabling functionality associated with a second circuit segment of the integrated
circuit design and includes an array of second device interconnect pads. Each one of the device
interconnect members is electrically connected directly between one of the first device interconnect
pads and a corresponding one of the second device interconnect pads.

100